

Figure 1. Internal schematic diagram

Features

Order code	$V_{DS} @ T_{Jmax}$	$R_{DS(on)} \text{ max}$	I_D
STF26N60M2	650 V	0.165 Ω	20 A
STFI26N60M2			

- Extremely low gate charge
- Excellent output capacitance (C_{oss}) profile
- 100% avalanche tested
- Zener-protected

Applications

- Switching applications
- L_{CC} converters, resonant converters

Description

These devices are N-channel Power MOSFETs developed using MDmesh™ M2 technology. Thanks to their strip layout and improved vertical structure, the devices exhibit low on-resistance and optimized switching characteristics, rendering them suitable for the most demanding high efficiency converters.

Table 1. Device summary

Order code	Marking	Package	Packaging
STF26N60M2	26N60M2	TO-220FP	Tube
STFI26N60M2		I ² PAKFP (TO-281)	

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1 Electrical ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{GS}	Gate-source voltage	± 25	V
I_D	Drain current (continuous) at $T_C = 25^\circ\text{C}$	20 ⁽¹⁾	A
I_D	Drain current (continuous) at $T_C = 100^\circ\text{C}$	13 ⁽¹⁾	A
$I_{DM}^{(2)}$	Drain current (pulsed)	80 ⁽¹⁾	A
P_{TOT}	Total dissipation at $T_C = 25^\circ\text{C}$	30	W
$dv/dt^{(3)}$	Peak diode recovery voltage slope	15	V/ns
$dv/dt^{(4)}$	MOSFET dv/dt ruggedness	50	V/ns
V_{ISO}	Insulation withstand voltage (RMS) from all three leads to external heat sink ($t = 1 \text{ s}$; $T_C = 25^\circ\text{C}$)	2500	V
T_{stg}	Storage temperature	- 55 to 150	$^\circ\text{C}$
T_j	Operating junction temperature		

1. Limited by maximum junction temperature.
2. Pulse width limited by safe operating area.
3. $I_{SD} \leq 22 \text{ A}$, $di/dt \leq 400 \text{ A}/\mu\text{s}$; V_{DS} peak < $V_{(BR)DSS}$, $V_{DD} = 400 \text{ V}$.
4. $V_{DS} \leq 480 \text{ V}$

Table 3. Thermal data

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case max	4.2	$^\circ\text{C/W}$
$R_{thj-amb}$	Thermal resistance junction-ambient max	62.5	$^\circ\text{C/W}$

Table 4. Avalanche characteristics

Symbol	Parameter	Value	Unit
I_{AR}	Avalanche current, repetitive or not repetitive (pulse width limited by T_{jmax})	3.8	A
E_{AS}	Single pulse avalanche energy (starting $T_j=25^\circ\text{C}$, $I_D = I_{AR}$; $V_{DD} = 50 \text{ V}$)	250	mJ

2 Electrical characteristics

($T_C = 25^\circ\text{C}$ unless otherwise specified)

Table 5. On /off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(\text{BR})\text{DSS}}$	Drain-source breakdown voltage	$I_D = 1 \text{ mA}, V_{GS} = 0$	600			V
I_{DSS}	Zero gate voltage drain current ($V_{GS} = 0$)	$V_{DS} = 600 \text{ V}$			1	μA
		$V_{DS} = 600 \text{ V}, T_C = 125^\circ\text{C}$			100	μA
I_{GSS}	Gate-body leakage current ($V_{DS} = 0$)	$V_{GS} = \pm 25 \text{ V}$			± 10	μA
$V_{GS(\text{th})}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	2	3	4	V
$R_{DS(\text{on})}$	Static drain-source on-resistance	$V_{GS} = 10 \text{ V}, I_D = 11 \text{ A}$		0.145	0.165	Ω

Table 6. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	$V_{DS} = 100 \text{ V}, f = 1 \text{ MHz}, V_{GS} = 0$	-	TBD	-	pF
C_{oss}	Output capacitance		-	TBD	-	pF
C_{rss}	Reverse transfer capacitance		-	TBD	-	pF
$C_{oss \text{ eq.}}^{(1)}$	Equivalent output capacitance	$V_{DS} = 0 \text{ to } 480 \text{ V}, V_{GS} = 0$	-	TBD	-	pF
R_G	Intrinsic gate resistance	$f = 1 \text{ MHz}$ open drain	-	TBD	-	Ω
Q_g	Total gate charge	$V_{DD} = 480 \text{ V}, I_D = 22 \text{ A}, V_{GS} = 10 \text{ V}$ (see Figure 15)	-	TBD	-	nC
Q_{gs}	Gate-source charge		-	TBD	-	nC
Q_{gd}	Gate-drain charge		-	TBD	-	nC

1. $C_{oss \text{ eq.}}$ is defined as a constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS}

Table 7. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(\text{on})}$	Turn-on delay time	$V_{DD} = 300 \text{ V}, I_D = 11 \text{ A}, R_G = 4.7 \Omega, V_{GS} = 10 \text{ V}$ (see Figure 14 and Figure 19)	-	TBD	-	ns
t_r	Rise time		-	TBD	-	ns
$t_{d(\text{off})}$	Turn-off delay time		-	TBD	-	ns
t_f	Fall time		-	TBD	-	ns

Table 8. Source drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current		-		20	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		80	A
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 22 \text{ A}, V_{GS} = 0$	-		1.6	V
t_{rr}	Reverse recovery time	$I_{SD} = 22 \text{ A}, di/dt = 100 \text{ A}/\mu\text{s}$ $V_{DD} = 60 \text{ V}$ (see <i>Figure 19</i>)	-	TBD		ns
Q_{rr}	Reverse recovery charge		-	TBD		μC
I_{RRM}	Reverse recovery current		-	TBD		A
t_{rr}	Reverse recovery time	$I_{SD} = 22 \text{ A}, di/dt = 100 \text{ A}/\mu\text{s}$ $V_{DD} = 60 \text{ V}, T_j = 150^\circ\text{C}$ (see <i>Figure 19</i>)	-	TBD		ns
Q_{rr}	Reverse recovery charge		-	TBD		μC
I_{RRM}	Reverse recovery current		-	TBD		A

1. Pulse width limited by safe operating area.
2. Pulsed: pulse duration = 300 μs , duty cycle 1.5%

3 Test circuits

Figure 2. Switching times test circuit for resistive load

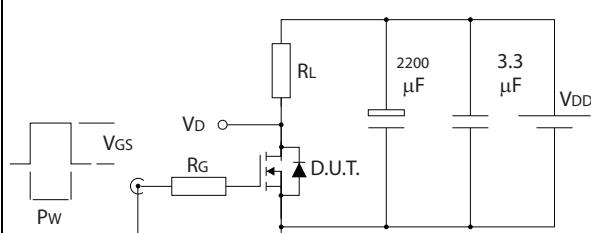


Figure 3. Gate charge test circuit

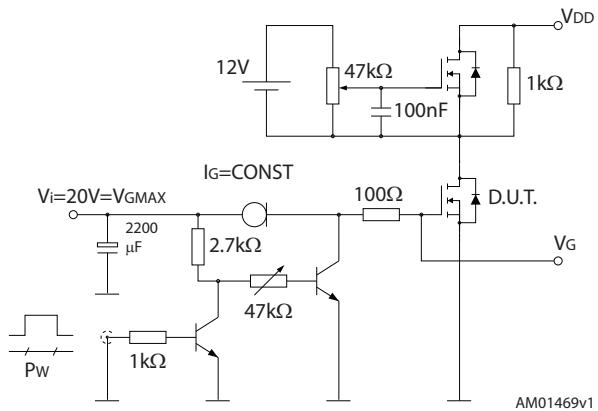


Figure 4. Test circuit for inductive load switching and diode recovery times

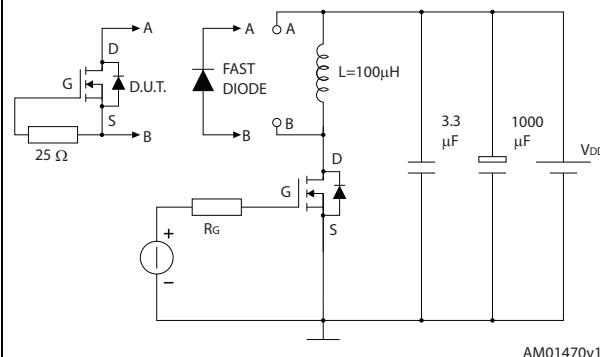


Figure 5. Unclamped inductive load test circuit

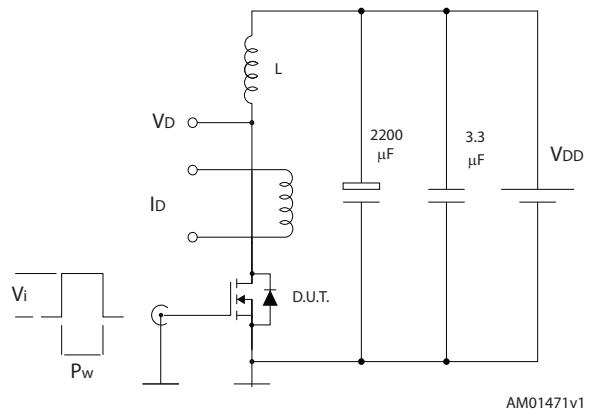


Figure 6. Unclamped inductive waveform

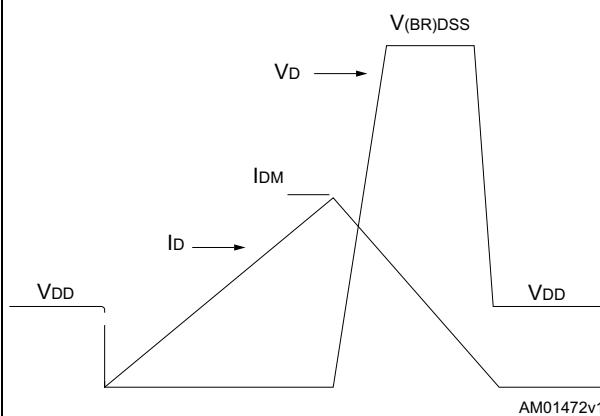
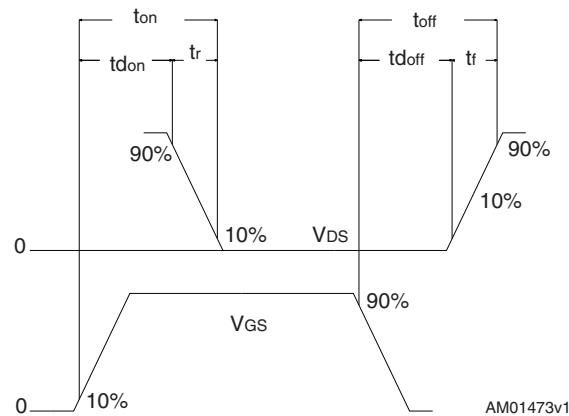


Figure 7. switching time waveform



4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com.
ECOPACK® is an ST trademark.

4.1 TO-220FP package information

Figure 8. TO-220FP outline

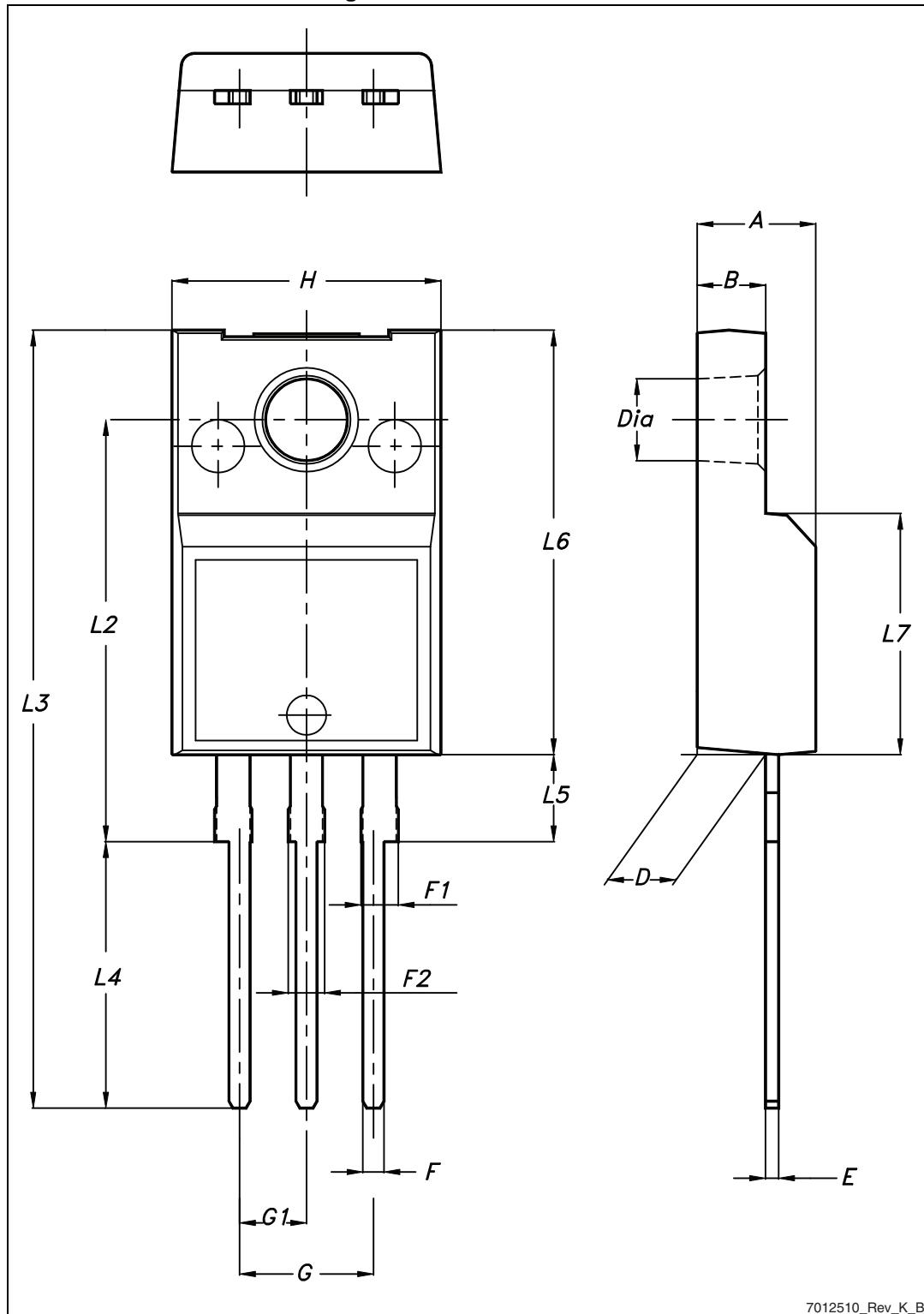


Table 9. TO-220FP mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.4		4.6
B	2.5		2.7
D	2.5		2.75
E	0.45		0.7
F	0.75		1
F1	1.15		1.70
F2	1.15		1.70
G	4.95		5.2
G1	2.4		2.7
H	10		10.4
L2		16	
L3	28.6		30.6
L4	9.8		10.6
L5	2.9		3.6
L6	15.9		16.4
L7	9		9.3
Dia	3		3.2

4.2 I²PAK (TO-281) package information

Figure 9. I²PAKFP (TO-281) outline

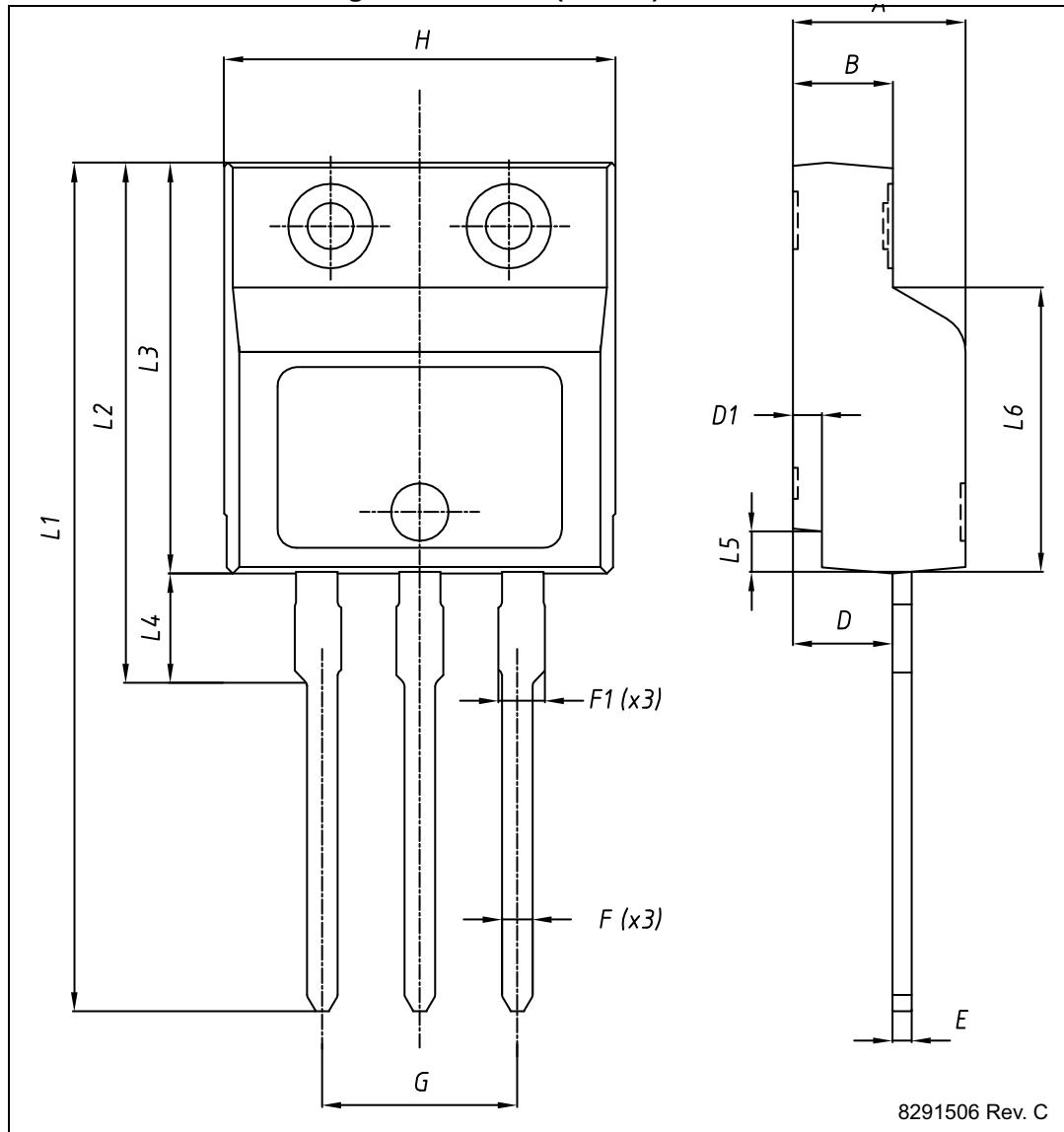


Table 10. I²PAKFP (TO-281) mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
B	2.50		2.70
D	2.50		2.75
D1	0.65		0.85
E	0.45		0.70
F	0.75		1.00
F1			1.20
G	4.95		5.20
H	10.00		10.40
L1	21.00		23.00
L2	13.20		14.10
L3	10.55		10.85
L4	2.70		3.20
L5	0.85		1.25
L6	7.50	7.60	7.70

5 Revision history

Table 11. Document revision history

Date	Revision	Changes
30-Mar-2015	1	First release.

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